

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	150	257/e29.324	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:24
L2	6294	257/678	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:26
L3	1715	257/414	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:28
L4	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover \$3) and plug with (seal \$3 or cover\$3) and hermetica\$3	USPAT	OR	OFF	2009/05/05 21:31
L5	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover \$3) and plug with (seal \$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:31
L6	4	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover \$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover \$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:31

L7	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) same (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover \$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
L8	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover \$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
L9	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrific\$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover \$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
L10	4	(semiconductor or die or dice or chip or IC) and micro near cavity and (sacrific\$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover \$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
L11	11	("20040053434" "20040065932" "20040126953" "5329110" "5597957" "6274440" "6582569" "6590280" "6636002" "6787387" "6924485").PN. OR ("7364932").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:37

L12	23	("4115719" "4147929" "4148050" "4534099" "4557037" "4758734" "4826777" "4925805" "4990827" "5098856" "5264693").PN. OR ("5329110").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:42
L13	14	("2867729" "3310701" "3435233" "3475076" "3873829" "3896305").PN. OR ("4147929").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:44
L14	1810	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:46
L15	258	(semiconductor or die or dice or chip or IC) and cavity and (sacrific\$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:46
L16	19	("20020075094" "20020171517" "20030047533" "20030155643" "20040173886" "20050074919" "5090254" "5589082" "6118164" "6133807" "6444135" "6452124" "6452238" "6472739" "6621387" "6635509" "6673697" "6686820"	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:50

			"7102472").PN. OR ("7381583").URPN.			
L17	1102	257/417	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:54
L18	75	("4918032" "4997521").PN. OR ("5589082").URPN.	US_PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:55
L19	326	257/420	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:00
L20	999	257/419	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:09
L21	445	257/418	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:10
L22	324	257/619	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:12
L23	2438	438/48	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:16
L24	1252	438/50	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:19

L26	1355	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:28
S1	5	"5,477,008".pn. or "20040065932" or "20040028849"	US-PGPUB; USPAT	OR	OFF	2008/06/09 07:08
S2	20	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or hermetica\$3)	USPAT	OR	ON	2008/06/09 07:10
S3	18	("4838088" "5188983" "5589082" "5631428" "5668033" "5783749" "5937275" "5952572" "6133146" "6140144" "6232150" "6265246" "6297072" "6335224" "6635509").PN. OR ("6902656").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S4	7	("5025346" "5028983" "5454158" "5523619" "5686697" "5822856" "6178093").PN. OR ("6779247").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S5	40	("5589082" "5668033" "5783749" "5937275" "5952572" "6140144" "6232150" "6265246" "6297072" "6335224").PN. OR ("6635509").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15

S7	6	("5589082" "5963788" "6174820" "6429755" "6628177" "6635509").PN. OR ("7002436").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:23
S8	68	("4918032" "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:31
S11	194	("20010001931" "20010009110" "20010034076" "20020016058" "20020135047" "20040016989" "20040065932" "4665610" "4674319" "4766666" "4849071" "4945769" "4990462" "5075253" "5139624" "5156903" "5338416" "5445991" "5455547" "5461916" "5470797" "5491604" "5504026" "5510156" "5517123" "5537083" "5540095" "5583290" "5589082" "5604312" "5613611" "5616514" "5620931" "5627317" "5627318" "5631422" "5640039" "5679436" "5683591" "5703293" "5721377" "5723353" "5728936"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:41

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S12	1	"20070126068"	US_PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:52
S13	67	257/E29.324	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:56

S14	1497	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:58
S15	1599	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:59
S16	1033	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:11
S17	424	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:28
S18	672	polysilicon with polymer	USPAT	OR	OFF	2008/06/09 08:34
S19	4	polysilicon with polymerized near material	USPAT	OR	OFF	2008/06/09 08:34
S20	27	polysilicon with polymerized	USPAT	OR	OFF	2008/06/09 08:35
S21	3437	polysilicon with glass	USPAT	OR	OFF	2008/06/09 08:38
S22	937	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:41
S23	315	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:49
S24	288	polysilicon near glass	USPAT	OR	OFF	2008/06/09 08:49

S25	5685	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:01
S26	301	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:25
S27	0	porous near silicon with photoresis	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S28	72	porous near silicon with photoresist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S29	2112	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:50
S30	1095	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:53
S31	0	photoresists with plug same micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S32	0	photoresists with plug and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54

S33	0	photoresists with (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S34	0	photoresists same (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S35	4008	photoresist with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S36	326	photoresist near material with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S37	1196	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 10:17
S38	798	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide	USPAT	OR	ON	2008/12/29 22:30
S39	32	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide and mems	USPAT	OR	ON	2008/12/29 22:30
S40	119	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S41	6051	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33

S42	1614	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:34
S43	4	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with (fill\$3 or seal \$3) with polyimide and mems	USPAT	OR	ON	2008/12/29 22:36
S44	1727	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:46
S45	1076	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:23
S46	322	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:50
S47	870	polysilicon with polymer	USPAT	OR	ON	2008/12/30 13:55
S48	28	polysilicon with made with polymer	USPAT	OR	ON	2008/12/30 13:55
S49	968	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:08
S50	440	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:12
S51	14	polysilicon with part with polymer	USPAT	OR	ON	2008/12/30 14:13

S52	315	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:47
S53	13	(semiconductor or die or dice or chip or IC) and micro near cavity with MEMS	USPAT	OR	ON	2008/12/30 14:51
S54	2312	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:17
S55	1188	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:26
S56	92	polymer near polysilicon	USPAT	OR	ON	2008/12/30 16:07
S57	1293	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:14

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